

MSKSEMI

SEMICONDUCTOR



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Product data sheet

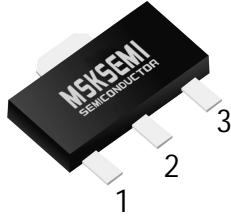
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FEATURES

- High Collector Current
- Complementary to PXT8050

SOT-89

1. BASE
2. COLLECTOR
3. EMITTER



| Symbol | Parameter | Value | Unit |
|-----------------|---|---------|---------------|
| V_{CBO} | Collector-Base Voltage | -40 | V |
| V_{CEO} | Collector-Emitter Voltage | -25 | V |
| V_{EBO} | Emitter-Base Voltage | -5 | V |
| I_C | Collector Current -Continuous | -1.5 | A |
| P_C | Collector Power Dissipation | 0.5 | W |
| $R_{\theta JA}$ | Thermal Resistance From Junction To Ambient | 250 | $^{\circ}C/W$ |
| T_J | Junction Temperature | 150 | $^{\circ}C$ |
| T_{stg} | Storage Temperature | -55~150 | $^{\circ}C$ |

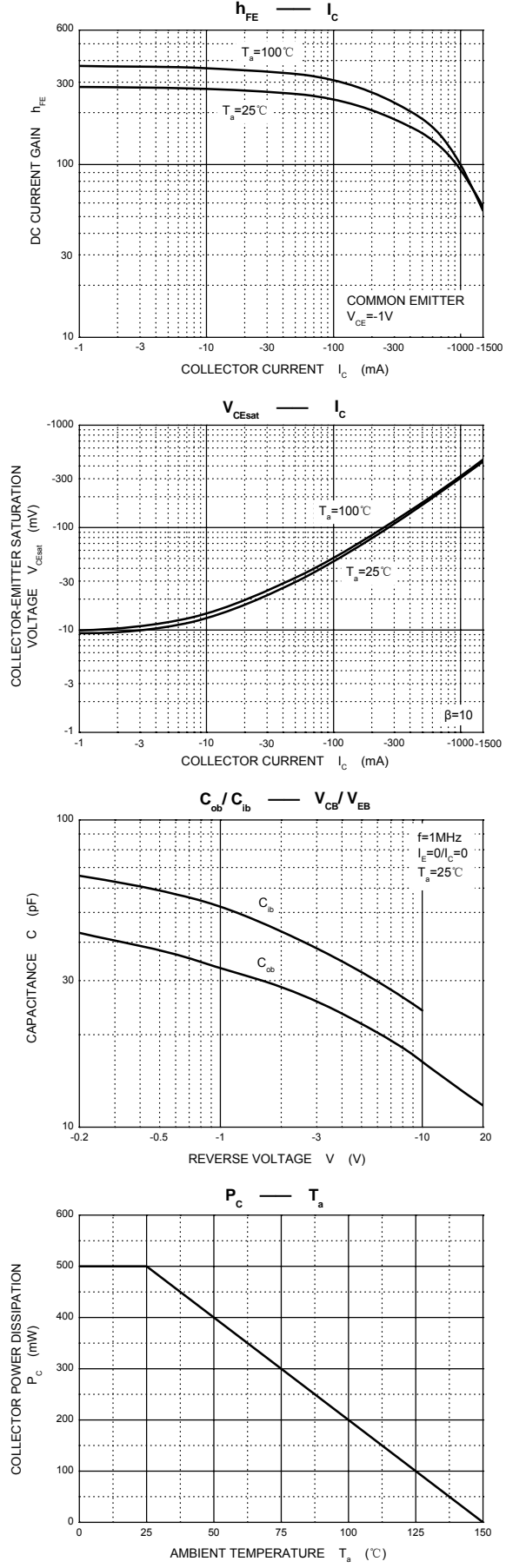
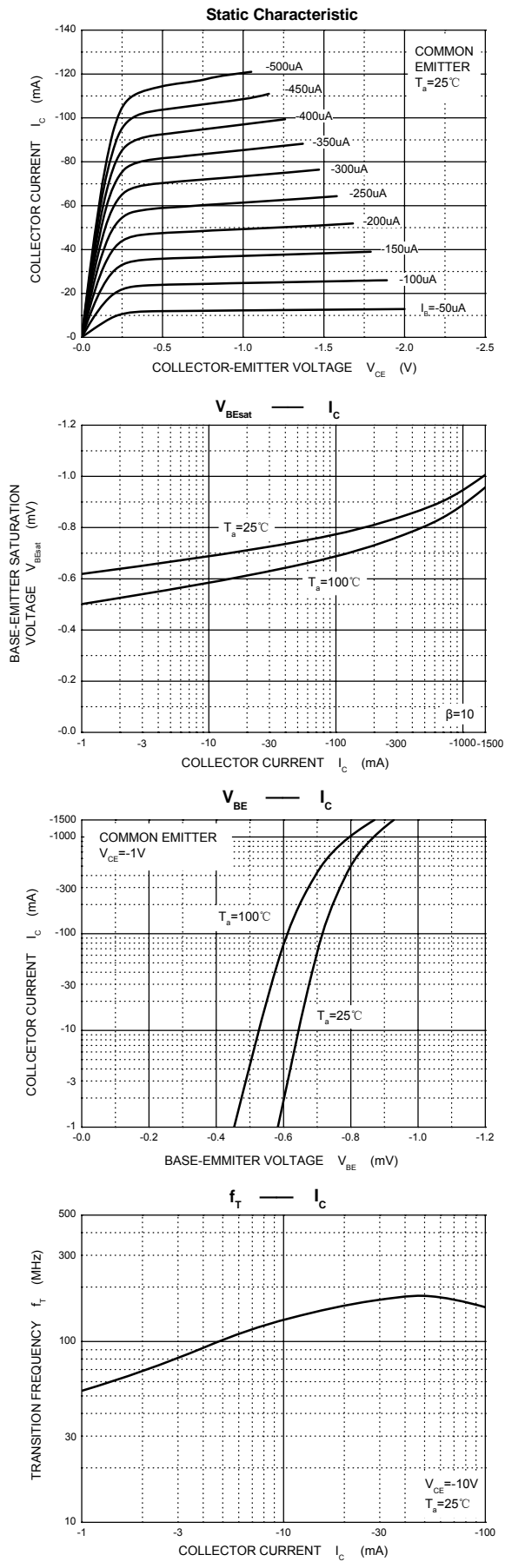
ELECTRICAL CHARACTERISTICS ($T_a=25^{\circ}C$ unless otherwise specified)

| Parameter | Symbol | Test conditions | Min | Typ | Max | Unit |
|--------------------------------------|---------------|-----------------------------------|-----|-----|------|------|
| Collector-base breakdown voltage | $V_{(BR)CBO}$ | $I_C=-100\mu A, I_E=0$ | -40 | | | V |
| Collector-emitter breakdown voltage | $V_{(BR)CEO}$ | $I_C=-1mA, I_B=0$ | -25 | | | V |
| Emitter-base breakdown voltage | $V_{(BR)EBO}$ | $I_E=-100\mu A, I_C=0$ | -5 | | | V |
| Collector cut-off current | I_{CBO} | $V_{CB}=-40V, I_E=0$ | | | -100 | nA |
| Emitter cut-off current | I_{EBO} | $V_{EB}=-5V, I_C=0$ | | | -100 | nA |
| DC current gain | $h_{FE(1)}$ | $V_{CE}=-1V, I_C=-100mA$ | 120 | | 400 | |
| | $h_{FE(2)}$ | $V_{CE}=-1V, I_C=-800mA$ | 40 | | | |
| Collector-emitter saturation voltage | $V_{CE(sat)}$ | $I_C=-800mA, I_B=-80mA$ | | | -0.5 | V |
| Base-emitter saturation voltage | $V_{BE(sat)}$ | $I_C=-800mA, I_B=-80mA$ | | | -1.2 | V |
| Base-emitter voltage | V_{BE} | $V_{CE}=-1V, I_C=-10mA$ | | | -1 | V |
| Transition frequency | f_T | $V_{CE}=-10V, I_C=-50mA, f=30MHz$ | 100 | | | MHz |
| Collector output capacitance | C_{ob} | $V_{CB}=-10V, I_E=0, f=1MHz$ | | | 20 | pF |

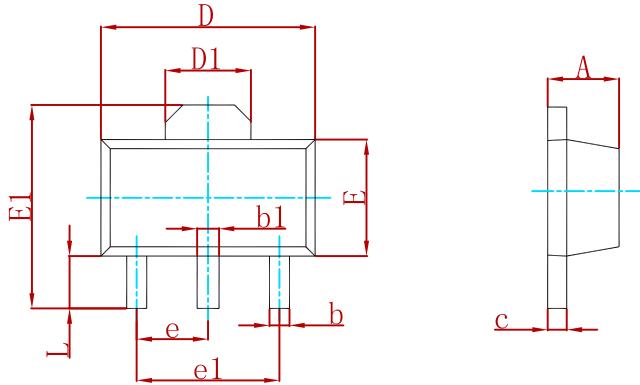
CLASSIFICATION OF $h_{FE(1)}$

| RANK | L | H | J |
|-------|-----------|-----------|-----------|
| RANGE | 120 - 200 | 200 - 350 | 300 - 400 |

Typical Characteristics

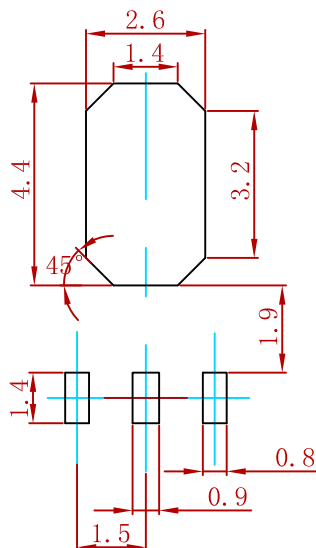


PACKAGE MECHANICAL DATA



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 1.400 | 1.600 | 0.055 | 0.063 |
| b | 0.320 | 0.520 | 0.013 | 0.020 |
| b1 | 0.400 | 0.580 | 0.016 | 0.023 |
| c | 0.350 | 0.440 | 0.014 | 0.017 |
| D | 4.400 | 4.600 | 0.173 | 0.181 |
| D1 | 1.550 REF. | | 0.061 REF. | |
| E | 2.300 | 2.600 | 0.091 | 0.102 |
| E1 | 3.940 | 4.250 | 0.155 | 0.167 |
| e | 1.500 TYP. | | 0.060 TYP. | |
| e1 | 3.000 TYP. | | 0.118 TYP. | |
| L | 0.900 | 1.200 | 0.035 | 0.047 |

Suggested Pad Layout



Note:
 1. Controlling dimension: in millimeters.
 2. General tolerance: ±0.05mm.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

| P/N | PKG | QTY |
|---------|--------|------|
| PXT8550 | SOT-89 | 1000 |

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